BAS21HT1G, BAS21HT3G, NSVBAS21HT1G, NSVBAS21HT3G

High Voltage Switching Diode

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These are Pb–Free Devices

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	250	Vdc
Repetitive Peak Reverse Voltage	V _{RRM}	250	Vdc
Peak Forward Current	١ _F	200	mAdc
Repetitive Peak Forward Current	I _{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current, 60 Hz	I _{FSM(surge)}	625	mAdc
$\label{eq:surge} \begin{array}{l} Non-Repetitive Peak Forward Current \\ (Square Wave, T_J = 25^\circ C \mbox{ prior to} \\ surge) \\ t = 1 \\ t = 10 \\ t = 100 \\ t = 1 \\ \end{array}$	I _{FSM}	20 20 10 4 1	A

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) $T_A = 25^{\circ}C$	P _D	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 Minimum Pad

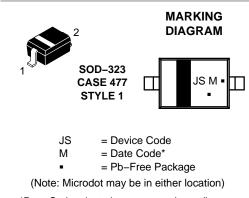


ON Semiconductor®

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HIGH VOLTAGE SWITCHING DIODE

1 0 2 CATHODE ANODE



*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS21HT1G, NSVBAS21HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
BAS21HT3G, NSVBAS21HT3G	SOD-323 (Pb-Free)	10000 / Tape & Reel

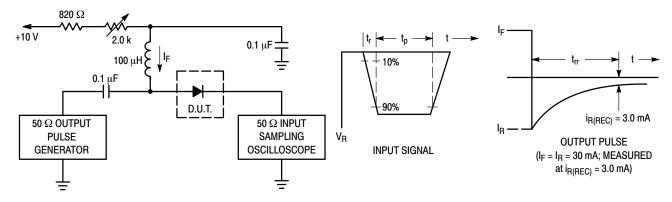
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

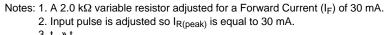
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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS		·		
Reverse Voltage Leakage Current ($V_R = 200 \text{ Vdc}$) ($V_R = 200 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$)	I _R		0.1 100	μAdc
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	V _(BR)	250	-	Vdc
Forward Voltage ($I_F = 100 \text{ mAdc}$) ($I_F = 200 \text{ mAdc}$)	VF		1000 1250	mV
Diode Capacitance ($V_R = 0, f = 1.0 \text{ MHz}$)	CD	-	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30$ mAdc, $R_L = 100 \Omega$)	t _{rr}	-	50	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



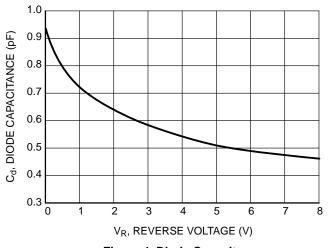


3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

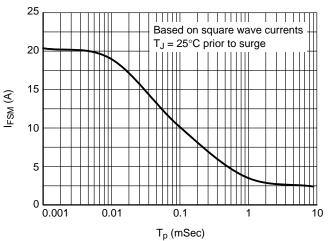
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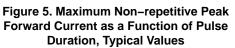
TYPICAL CHARACTERISTICS $T_A = -55^{\circ}C$ T_A = 155°C 25°C **REVERSE CURRENT (nA)** 155°C $T_A = 25^{\circ}C$ T_A = −55°C 200 300 FORWARD CURRENT (mA) **REVERSE VOLTAGE (V)** Figure 2. Forward Voltage Figure 3. Reverse Leakage



LORWARD VOLTAGE (mV)

Figure 4. Diode Capacitance

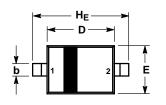


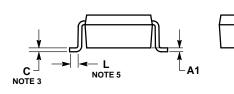


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PACKAGE DIMENSIONS

SOD-323 CASE 477-02 **ISSUE H**





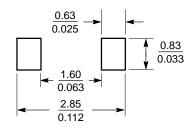
NOTES DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.

- CONTROLLING DIMENSION: MILLIMETERS. LEAD THICKNESS SPECIFIED PER L/F DRAWING 3.
- LEAD THORNESS PLATING.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
He	2 30	2 50	2 70	0 090	0.098	0 105

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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